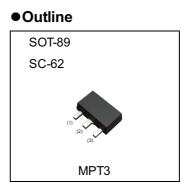
## 2SCR642P HZG

For gate drive(30V / 10A)

Parameter	Value
V <sub>CEO</sub>	30V
Ι <sub>C</sub>	3A



#### • Features • Inner circuit 1) Low saturation voltage,typically $V_{CE(sat)}=400 \text{mV}(\text{Max.})$ $(I_C/I_B=2A/100 \text{mA})$ 2) High speed switching 3) Suitable for gate drive circuit. 4) AEC-Q101 Qualified (1) $\circ$ (1) $\circ$ (1) $\circ$ (1) $\circ$ (1) $\circ$ (3) Emitter

## Application

## LOW FREQUENCY AMPLIFIER, HIGH SPEED SWITCHING, GATE DRIVE

## Packaging specifications

Part No.	Package	Taping code	Reel size (mm)	Tape width (mm)	Quantity (pcs)	Marking
2SCR642P HZG	MPT3 (SOT-89)	T100	180	12	1000	NP

## •Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Values	Unit
Collector-base voltage	V <sub>CBO</sub>	30	V
Collector-emitter voltage		30	V
Emitter-base voltage	V <sub>EBO</sub>	6	V
	Ι <sub>C</sub>	3	Α
Collector current	I <sub>CP</sub> *1	10	Α
	P <sub>D</sub> *2	0.5	W
Power dissipation	P <sub>D</sub> *3	2.0	W
Junction temperature	Tj	150	°C
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C

## • Electrical characteristics ( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV <sub>CBO</sub>	Ι <sub>C</sub> = 100μΑ	30	-	-	V
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	30	-	-	V
Emitter-base breakdown voltage	$BV_{EBO}$	Ι <sub>Ε</sub> = 100μΑ	6	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 30V	-	-	1	μA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 4V	-	-	1	μA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub> *4	I <sub>C</sub> = 2A, I <sub>B</sub> = 100mA	-	200	400	mV
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 2V, I <sub>C</sub> = 500mA	200	-	500	-
Transition frequency	f <sub>T</sub> *4	V <sub>CE</sub> = 10V, I <sub>E</sub> = -100mA, f = 100MHz	-	250	-	MHz
Output capacitance	C <sub>ob</sub>	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0A, f = 1MHz	-	25	-	pF
Turn-On time	t <sub>on</sub>	I <sub>C</sub> = 2.5A, I <sub>B1</sub> = 250mA,	-	40	-	ns
Storage time	t <sub>stg</sub>	I <sub>B2</sub> = -250mA, V <sub>CC</sub> ≃ 10V,	-	320	-	ns
Fall time	t <sub>f</sub>	R <sub>L</sub> = 3.9Ω See test circuit	-	25	-	ns

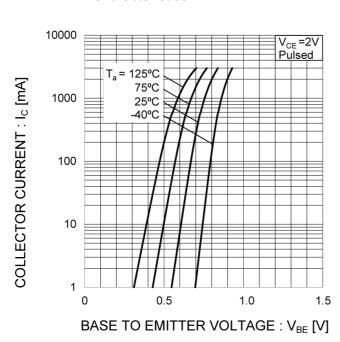
\*1 Pw=1ms, Single Pulse

\*2 Each terminal mounted on a reference land.

\*3 Mounted on a ceramic board.(40×40×0.7mm)

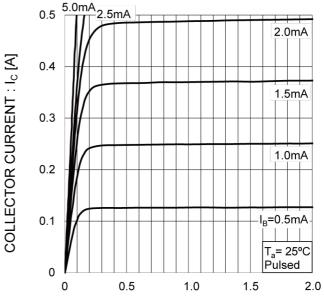
\*4 Pulsed

## • Electrical characteristic curves(T<sub>a</sub> = 25°C)



### Fig.1 Ground Emitter Propagation Characteristics

Fig.2 Typical Output Characteristics



COLLECTOR TO EMITTER VOLTAGE :  $V_{CE}$  [V]

## Fig.3 DC Current Gain vs. Collector Current (I)

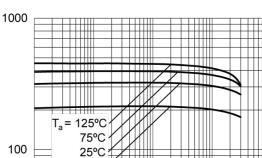
40°C

10

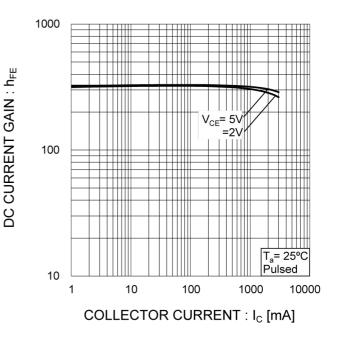
100

COLLECTOR CURRENT : Ic [mA]

DC CURRENT GAIN : hFE



## Fig.4 DC Current Gain vs. Collector Current (II)



10

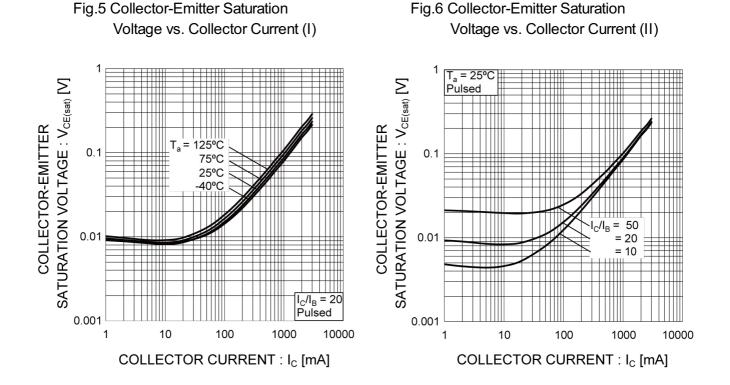
1

V<sub>CE</sub>= 2V Pulsed

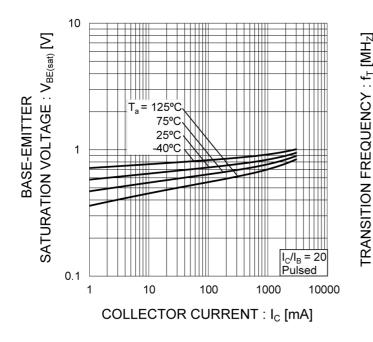
10000

1000

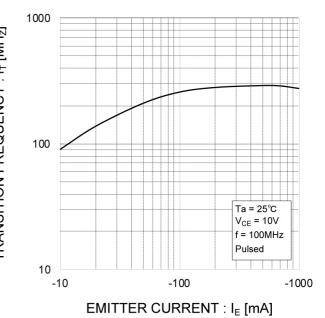
## •Electrical characteristic curves(T<sub>a</sub> = 25°C)



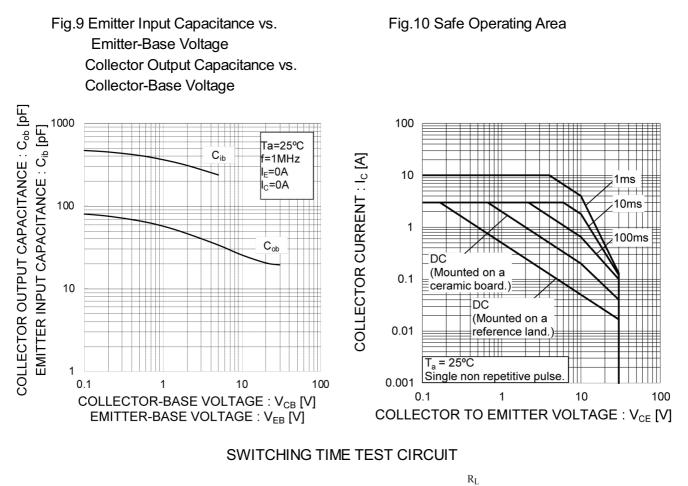
# Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

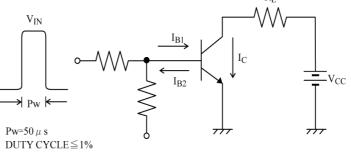


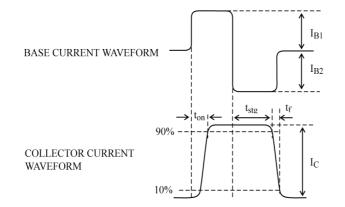
## Fig.8 Gain Bandwidth Product vs. Emitter Current



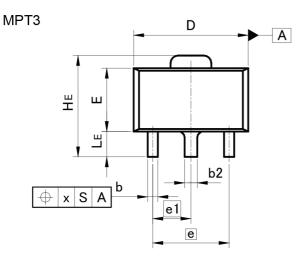
## • Electrical characteristic curves(T<sub>a</sub> = 25°C)

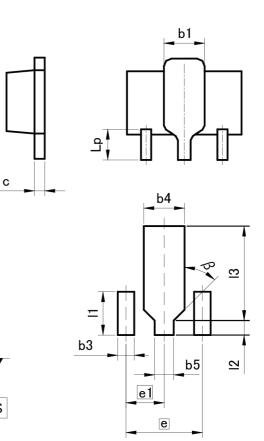






## Dimensions





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INCHES			
	MIN	MAX	MIN	MAX		
A	1.40	1.50	0.055	0.059		
b	0.30	0.50	0.012	0.020		
b1	1.50	1.70	0.059	0.067		
b2	0.40	0.60	0.016	0.024		
с	0.35	0.50	0.014	0.020		
D	4.40	4.70	0.173	0.185		
E	2.40	2.70	0.094	0.106		
е	3.0	00	0.118			
e1	1.50		0.059			
HE	3.70	4.30	0.146	0.169		
LE	0.80	1.20	0.031	0.047		
Lp	1.01	1.41	0.040	0.056		
x	-	0.15	—	0.006		
У	-	0.10		0.004		
DIM	MILIMETERS		INC	HES		
	MIN	MAX	MIN	MAX		
b3	-	0.65	-	0.026		
b4	-	1.70	-	0.067		
b5	-	0.75	-	0.030		
1	-	1.71	_	0.067		
12	_	0.58	_	0.023		
13	-	3.72	I	0.146		
β	45°		45°			

∢

S

\_\_ **y** S

Dimension in mm/inches

## Notice

#### **Precaution on using ROHM Products**

 If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA
CLASSII	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSI	CLASSII	CLASSⅢ

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[a] Installation of protection circuits or other protective devices to improve system safety

[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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